



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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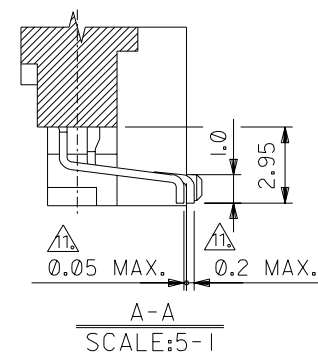
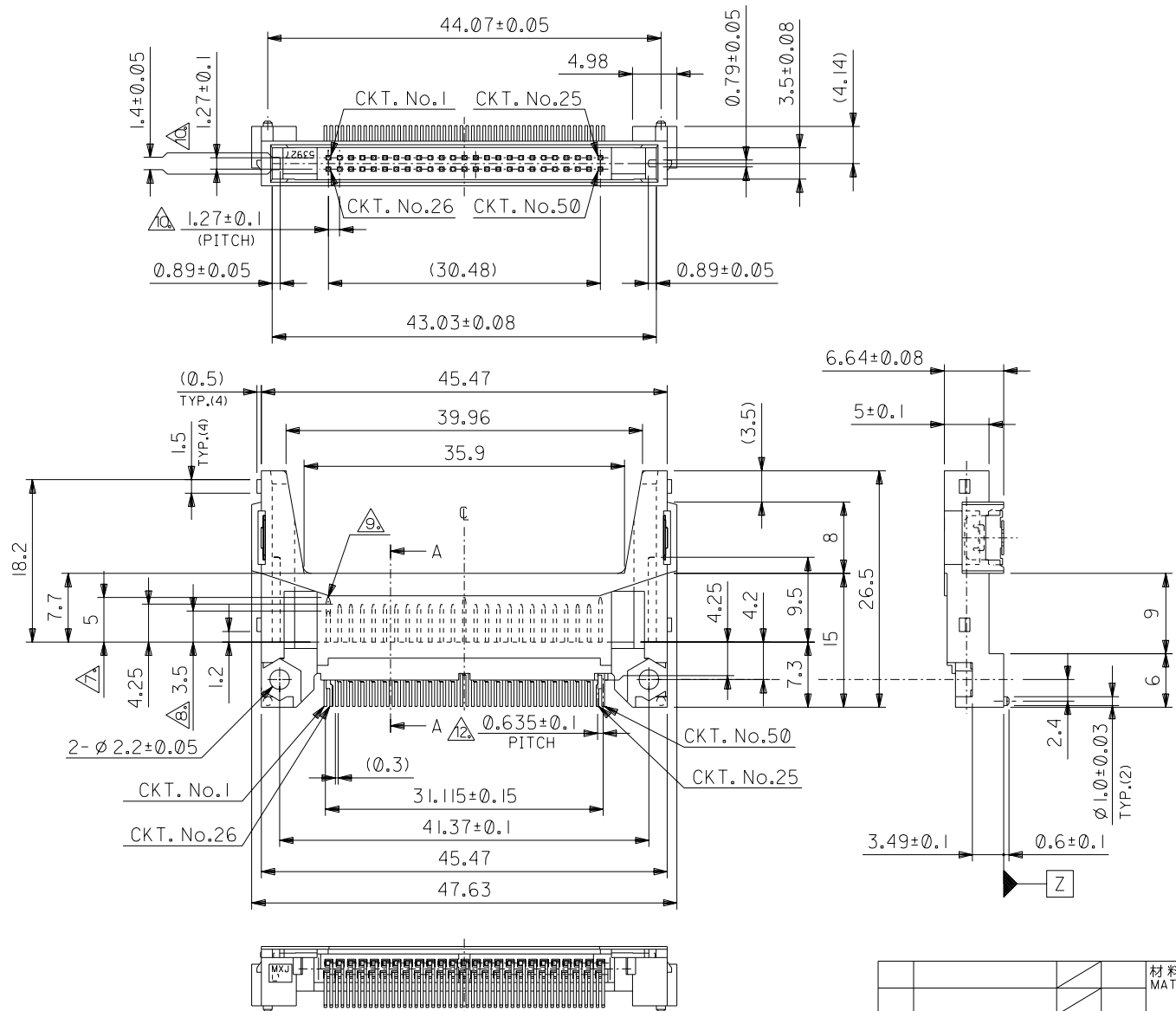
DWG. NO.  
SD-53927-001

E

D

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

A



53927-**19	53927-5019
MODEL No.	MATERIAL No.

材料 MATERIAL		SEE NOTES	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH		SEE NOTES	REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE		— # —	TITLE 名称 CFA CARD CONN. 50P HEADER ASS'Y (REVERSE TYPE) -LEAD FREE-	
被覆外径 INS. RANGE		— # —	DWG. NO. SHEET 1 OF 2 REV	
DRAWN BY '04/05/17 T.UENO		CHK'D BY '04/05/17 M.SASAO	SD-53927-001 0	
APP'D. BY '04/05/17 M.SASAO		尺 度 SCALE 2 - 1		
角度 ANGLE	$\pm 3^\circ$			
30以上 OVER	$\pm 0.3$			
10以上 OVER 30未滿 UNDER	$\pm 0.25$			
未滿 UNDER	$\pm 0.2$			
一般公差 GENERAL TOLERANCES	0	新規作成 RELEASED (J2004-4268)	DR. CHK. 日付 DATE	

DWG. NO. SD-53927-001

E

D

C

B

A

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

注)  
 NOTES 1. 材質  
 MATERIAL  
 ハウジング：ガラス入りLCP UL94V-0  
 HOUSING: LCP G.F. UL94V-0  
 ピン：リン青銅  
 PIN: PHOSPHOR BRONZE  
 ネール：リン青銅  
 NAIL: PHOSPHOR BRONZE

2. メッキ仕様  
 PLATING  
 PIN 接点部：パラジウムニッケル下地、金メッキ  
 CONTACT AREA: Au OVER Pd-Ni  
 半田付け部：錫メッキ  
 SOLDER TAIL AREA: TIN  
 下地メッキ：ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL

NAIL 錫メッキ  
 TIN  
 下地メッキ：ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL

3. 推奨基板厚：t0.8 MIN.  
 RECOMMENDED P.C.B. THICKNESS: t0.8 MIN.

4. 適合カード厚  
 RECOMMENDED CARD THICKNESS  
 接続部：3.3±0.1  
 CONNECTING AREA: 3.3±0.1

5. 適合カード幅：42.8±0.1  
 RECOMMENDED CARD WIDTH: 42.8±0.1

6. ハウジング色：白  
 HOUSING COLOR: WHITE

△7 寸法適用極：1,13,38,50  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS  
 1,13,38 AND 50.

△8 寸法適用極：25,26  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.

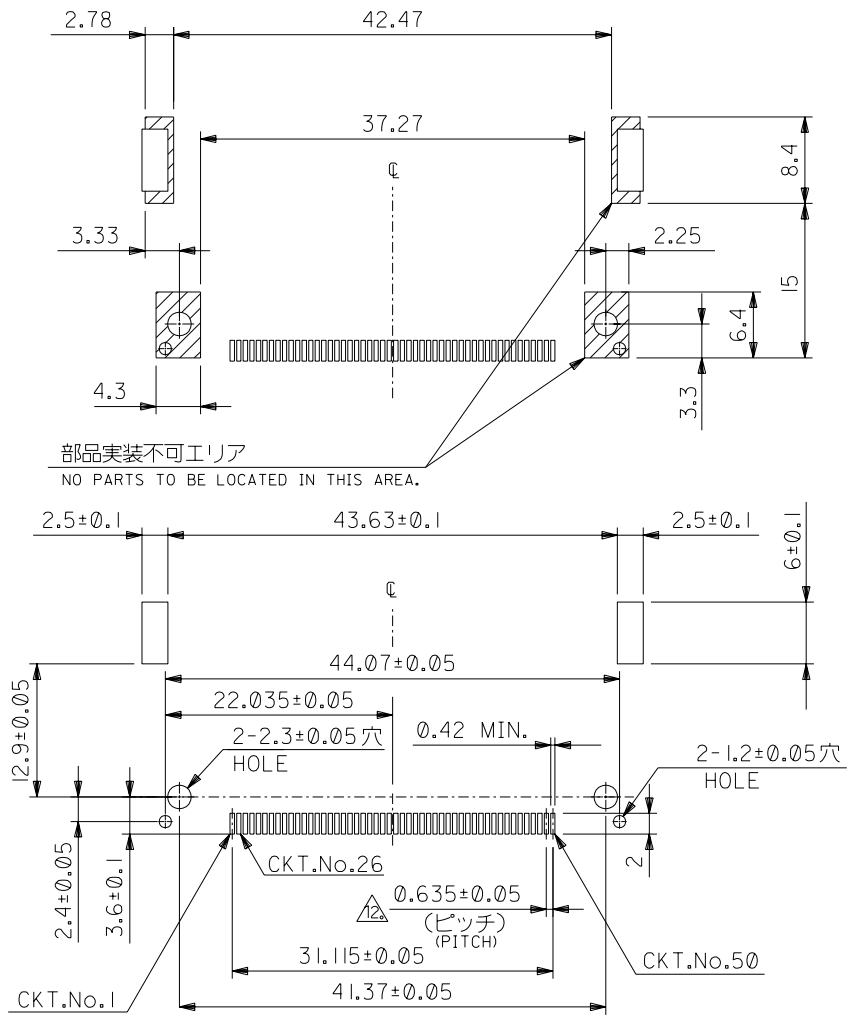
△9 ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。  
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1  
 WHEN MEASURED FROM PIN BASE.

△10 ピン根元に適用する。  
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

△11 ソルダータールは、Z面を基準とし上へ0.05下へ0.2の範囲にあり、  
 且つソルダータールの平坦度は、0.15 MAX.とし、テール先端にて測定する。  
 SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND 0.2 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF  
 SOLDER TAILS TO BE WITHIN 0.15.  
 MEASUREMENT POINT IS SOLDER TAILS TIP.

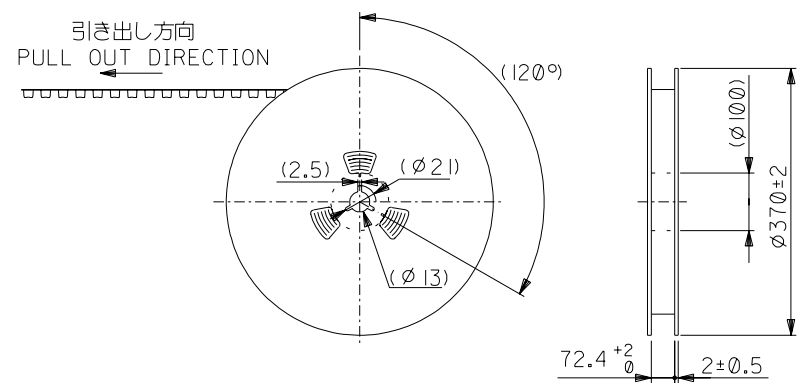
△12 公差非累積  
 NON-CUMULATIVE

13. 本製品は53927-\*\*10の鉛フリー一品である。  
 THIS PRODUCT IS LEAD FREE OF 53927-\*\*10.



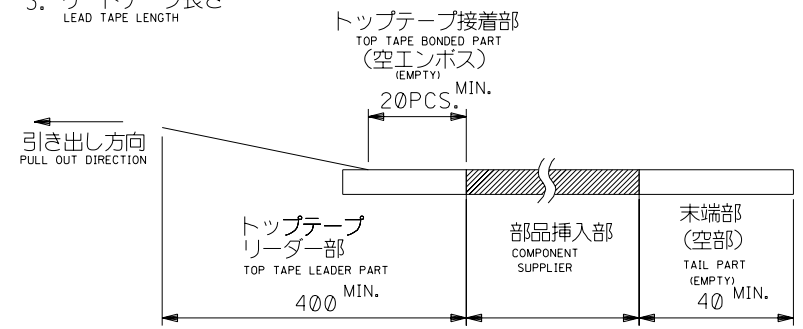
基板推奨寸法  
 RECOMMENDED P.C.B. LAYOUT

				材料 MATERIAL		— # —		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
				仕上げ FINISH		— # —		REVISE ONLY ON CAD SYSTEM	
				適用電線範囲 WIRE RANGE		— # —		TITLE 名称 CFA CARD CONN. 50P HEADER ASS'Y (REVERSE TYPE) -LEAD FREE-	
				被覆外径 INS. RANGE		— # —		DWG. NO. SHEET 2 OF 2 REV	
				DRAWN BY 04/05/17 T.UJENO		CHK'D BY 04/05/17 M.SASAO		SD-53927-001 0	
				APP'D BY 04/05/17 M.SASAO		尺度 SCALE 2 - 1			
角度 ANGLE	±3°			記号 LTR	変更内容 REVISION RECORD	日付 DATE			
30以上 OVER	+0.3			0	SEE SHEET 1 OF 2	11/11 M.S	04/05/17		
10以上 OVER 30 UNDER	+0.25								
10 UNDER	+0.2								
一般公差 GENERAL TOLERANCES									



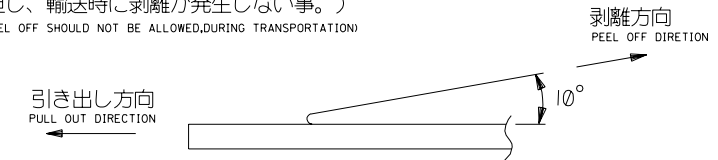
注)  
NOTES

- 製品番号 53927-5019 の詳細寸法については、SD-53927-001 を参照下さい。  
IN THE PACKAGE , PART NO. 53927-5019 DETAILED DIMENSIONS , SEE SD-53927-001
- 梱包数量 : 280 個/リール  
NUMBER OF CONNECTORS : 280 PCS/REEL
- リードテープ長さ  
LEAD TAPE LENGTH



- トップテープの剥離強度 : (剥離方向は下図参照)  
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
0.1~1.3N {10~130gf} : キャリアテープ幅72mm  
CARRIER TAPE WIDTH 72mm

尚、本規格値は、出荷時に適用。  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
(但し、輸送時に剥離が発生しない事。)  
(PEEL OFF SHOULD NOT BE ALLOWED DURING TRANSPORTATION)

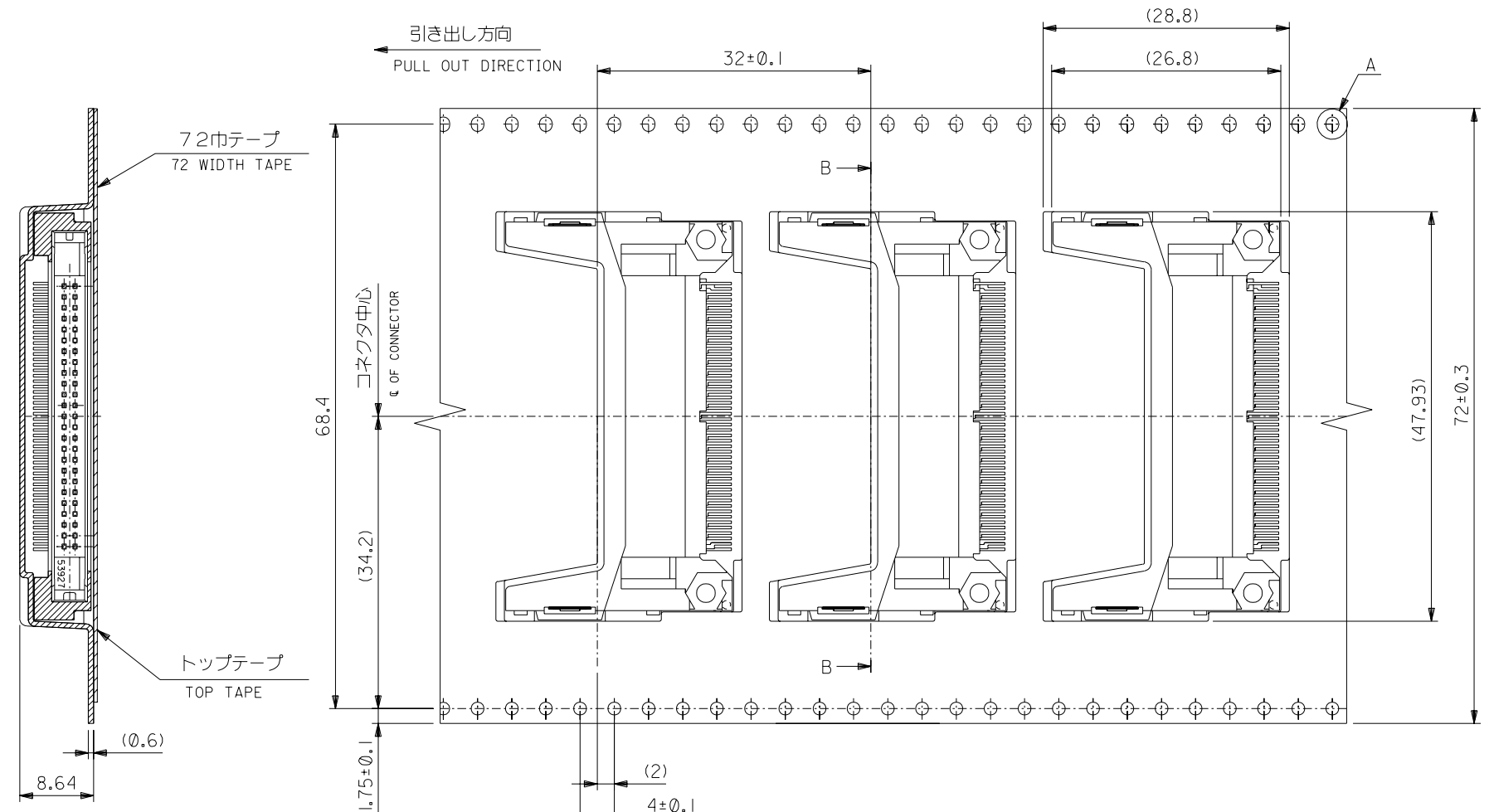


- 材料  
MATERIAL  
キャリアテープ : ポリプロピレン (PP)  
CARRIER TAPE : POLYPROPYLENE (PP)  
トップテープ : PET, PE, PEF  
TOP TAPE : PET, PE, PEF  
リール : 紙  
REEL : CARD BOARD

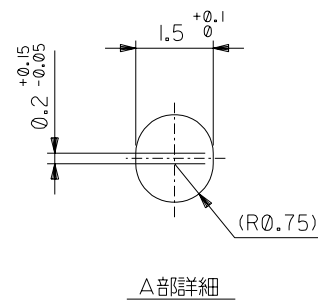
- 本製品は 53927-\*\*-18 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53927-\*\*-18.

53927-**-78	53927-5078	50
MODEL NO.	MATERIAL NO.	種数 NO. OF CKTS.

材料 MATERIAL		注参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH		---		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE		---		TITLE 名称 53927-5019 TAPING PACKAGE -LEAD FREE-	
被覆外径 INS. RANGE		---		DRAWN BY 04/05/17 T.UENO CHK'D BY 04/05/17 M.SASAO	
DRAWN BY 04/05/17 T.UENO		CHK'D BY 04/05/17 M.SASAO		DWG. NO. (SHEET 1 OF 2) REV	
APP'D BY 04/05/17 M.SASAO		尺度 SCALE		SD-53927-002 0	
角度 ANGLE	+30	記号 LTR	変更内容 REVISION RECORD	日付 DATE	尺度 SCALE
30 以上 OVER	+0.3	①	新規作成 (J2004-4268) RELEASED	04/05/17 T.UENO	---
10 以上 OVER 30 UNDER	+0.25				
未滿 UNDER	+0.2				
一般公差 GENERAL TOLERANCES					



断面 B - B  
SECTION B-B



角度 ANGLE	±30				材料 MATERIAL	注参照 SEE NOTES	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
30 以上 OVER	+0.3				仕上げ FINISH	—	
10 以上 30 未満 OVER 30 UNDER	+0.25				適用電線範囲 WIRE RANGE	—	TITLE 名称
10 未満 UNDER	+0.2				被覆外径 INS. RANGE	—	53927-5019
一般公差 GENERAL TOLERANCES		SEE SHEET 1 OF 2			DRAWN BY 04/05/17 T.UENO	CHK'D BY 04/05/17 M.SASAO	TAPING PACKAGE
記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE	APP'D BY 04/05/17 M.SASAO	尺度 SCALE	2 - 1	-LEAD FREE-
							DWG. NO. (SHEET 2 OF 2)
							SD-53927-002
							REV 0